

	Power Dissipation Derating ($T_a = 25^\circ\text{C}$)	$P_D/$	-3.33	mW/
Total Power Dissipation		P_{tot}	350	mW
Isolation Voltage		V_{iso}	5000	Vrms
Operating Temperature		T_{opr}	-55~100	
Storage Temperature		T_{stg}	-55~125	
Soldering Temperature		T_{sol}	260	

NOTE1:

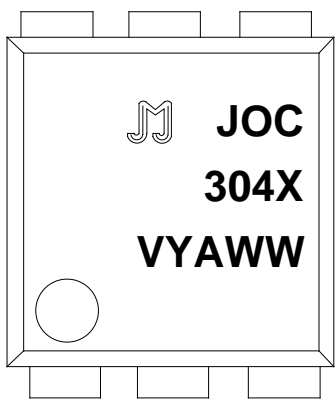
NOTE2:

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10\text{mA}$	-	1.27	2.2	V
	Reverse Current	I_R	$V_R=6\text{V}$	-	-	1	A
	Input Capacitance	C_{in}	$V=0, f=1\text{kHz}$	-	10	-	pF
Output	Peak Off-state Current, Either Direction	I_{OFF}	$V_{OFF}=400\text{V}, I_F=0$	-	-	100	nA
	Peak On-state Voltage, Either Direction	V_{TM}	$I_{TM}=100\text{mA}$	-	1.7	2.5	V
	Critical Rate of Rise of Off-state voltage	dV/dt	$V_{PEAK}=400\text{V}, I_F=0$	1000	-	-	
LED Trigger Current	JOC3041	I_{FT}	Terminal Voltage=3V $I_{TM}=100\text{mA}$ $I_{TM}=2$	-	-	15	mA
	JOC3042			-	-	10	
	JOC3043			-	-	5	
Holding Current		I_H					

Transfer Characteristics

ORDERING AND MARKING INFORMATION

MARKING INFORMATION			
			
ORDERING INFORMATION			
JOC304X(Y)(Z)-GV			
Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

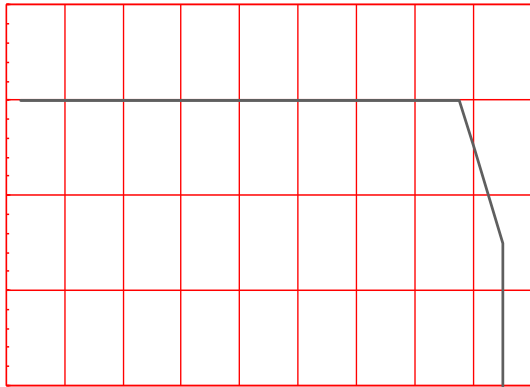


FIG.2: On-state Terminal Current vs. Ambient Temperature

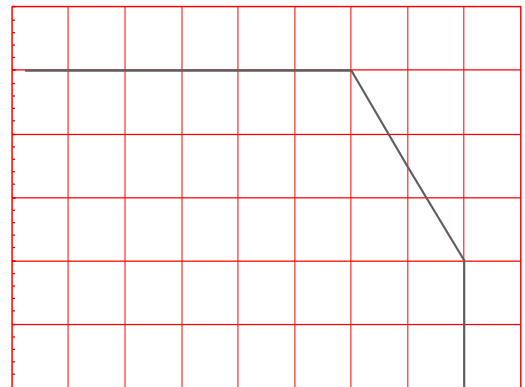


FIG.3: Forward Current vs. Forward Voltage

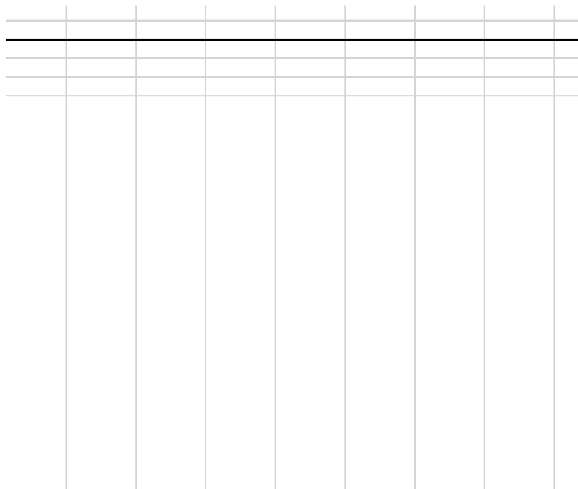


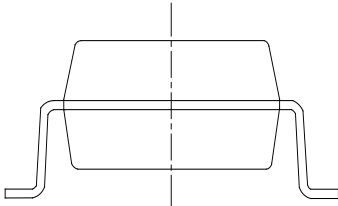
FIG.4: Normalized Off-state Terminal Current vs. Ambient Temperature

TEST CIRCUITS

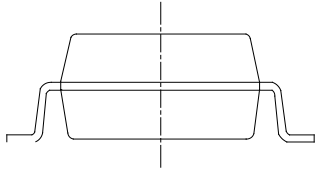
FIG.12: Test Circuits of Turn On Time

FIG.13: Waveforms of Turn On Time

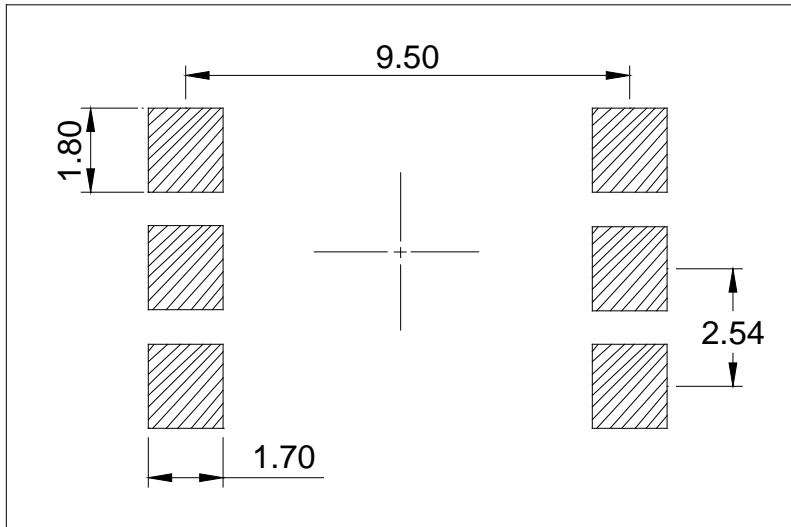
Option S Type:



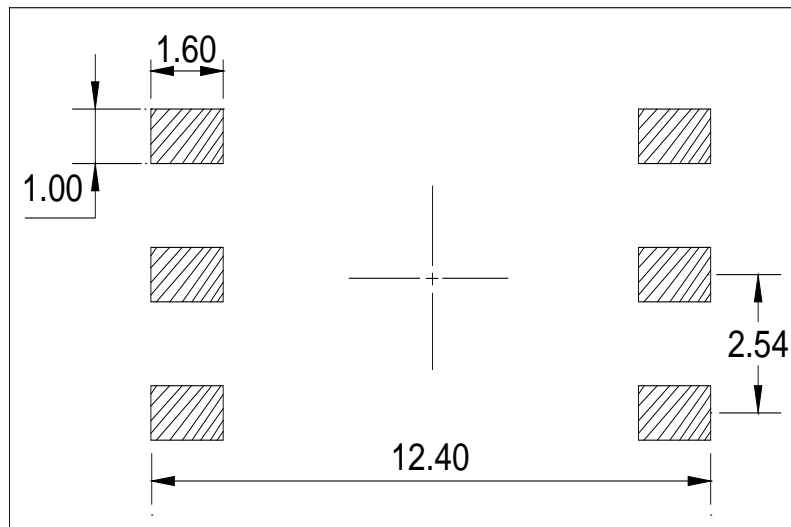
Option SLM Type: Dimensions Millimeters Inches Ref. Min. Typ. Max. Min. Typ. Max.



Option SL

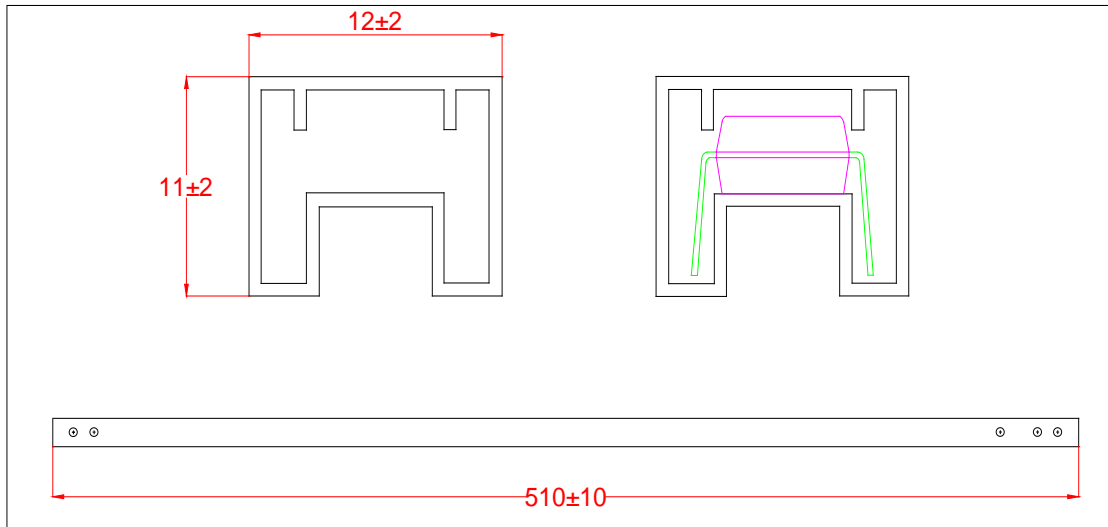


Option SLM

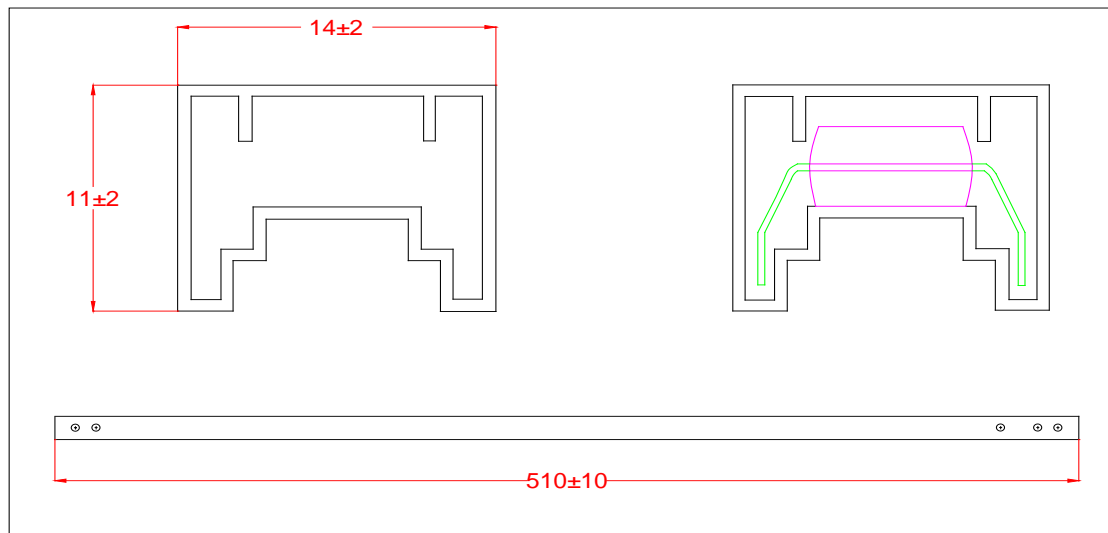


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

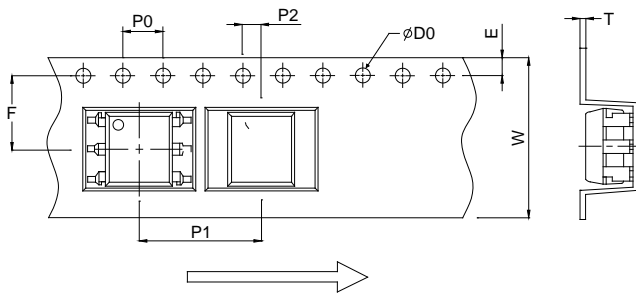
Standard DIP

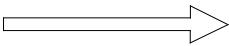
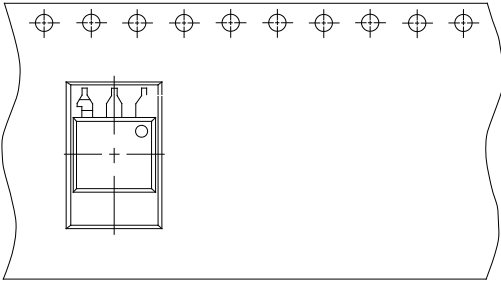


Option M

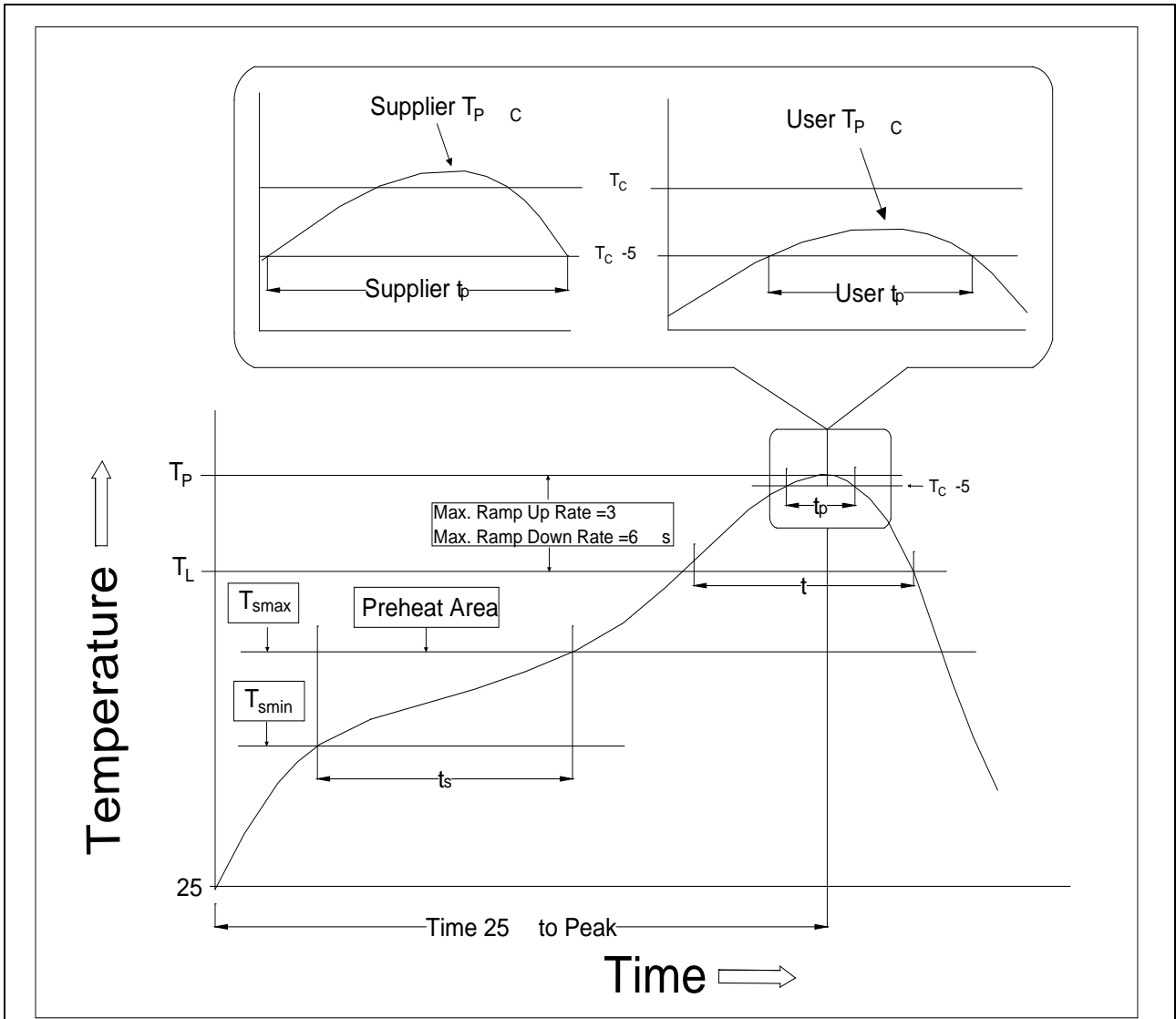


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)





REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150
Temperature Max. (T _{smax})	150	200
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3 °C/second max.	3 °C/second max.
Liquidus Temperature (T _L)	183	217
Time (t _L) Maintained Above (T _L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (t _P) within 5 °C of 260	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6	

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360± 5
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Document Revision History

Date	Revision	Changes
Apr.2, 2025	A.1.0	Last update
Nov.5, 2025	A.1.1	Add S&SLM package

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